



Flip Chip Substrates BT to ABF Conversion for Select Virtex-II Pro FPGA Devices

XCN10013 (v1.0) April 19 , 2010

Product Change Notice

Overview

The purpose of this notification is to announce conversion of substrate material changed from BT to ABF build-up for select Virtex[®]-II Pro FPGA device/package. There is no change to the form, fit, function or reliability with this change.

Description

For the below affected products, substrate materials will be converted from BT to ABF build-up. The reason for the change is the phase out of UV laser equipment support at substrate supplier. To ensure continuity of supply for flip chip products, BT will be replaced by ABF since UV laser is not required to form via's with ABF material. The ABF materials set has been already qualified and in production for other Virtex-II Pro FPGA, Virtex[®]-4 FPGA and Virtex[®]-5 FPGA products.

Products Affected

This change affects all speed, package, and temperature variations of the commercial (C) and industrial (I) grade devices. All SCD parts derived from base part are also affected. Affected part numbers are included in the following table(s):

Table 1: Product Changes

Xilinx Product	Package	Change Description
XC2VP70	FF(G)1704	Build-up materials set change from BT to ABF
XC2VP100	FF(G)1704	Build-up materials set change from BT to ABF

Note: All SCD parts are also affected.

Key Dates and Ordering Information

Xilinx will begin to cross-ship production using BT and ABF substrate materials on or after 90 days of PCN date.

Qualification Data

Qualification data & device reliability report for Virtex-II Pro FPGA devices is available in [UG116](#). The extended qualification data related to this PCN is available in [RPT141](#) located in 'Additional Document' section below.

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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Additional Documentation

Qualification Report (RPT141)
<https://secure.xilinx.com/webreg/clickthrough.do?cid=140202>

Device Reliability Report (UG116):
http://www.xilinx.com/support/documentation/user_guides/ug116.pdf

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
04/19/10	1.0	Initial release.

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